

Product/ Process Change Notification

1. PCN No.:	QPCN14014
2. Subject:	<i>FE (Front End) production location change & Die attach method change</i>
3. To:	<i>All involved customers</i>
4. Issued by:	<i>HQ (Headquarters) QRA. Owen Wang</i>
5. Issue date:	<i>10-Jul-2014</i>
6. Proposed first ship date for change:	<i>10-Oct-2014</i>
7. Affected Product Identification	
<i>DSD (Discrete Semiconductor Device) Package as ITO-220AB See attached details TSC Part-No. list.</i>	
8. Change Description : (OLD Vs. NEW Comparison)	
Old:	New:
<ul style="list-style-type: none"> ➤ <i>Subcon FE located in Taiwan will be discontinued.</i> ➤ <i>Die attach method: Wire Bond</i> 	<ul style="list-style-type: none"> ➤ <i>New FE subcon located in Taiwan</i> ➤ <i>Die attach method: Clip Bond</i>
9. Reason for Change:	
<i>Die attach change.</i>	
10. Anticipated Impact: (form, fit, function, quality or reliability)	
1. Product outline: 2. Inner construction changed: 3. Electrical specifications: 4. Reliability performance: 5. Data sheet: 6. Packing code (order code): 7. Identification/Traceability:	<i>Not Available Die attach method change No change No change No change No change By date code</i>
11. Qualification plan/result:	
Refer to PPAP Comparison report	<i>Available on demand See attached file</i>
12. Sample availability date:	<i>15-Aug-2014</i>
13. Tentative implementation date:	<i>15-Aug-2014</i>
14. Remarks	
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)	15-Aug-2014
16. Approved by:	<i>Quayer Chen</i>